

**BONDING +  
SEALING +  
ENCAPSULATION**

**Kisling**



# 7500 + 7920

**7500 + 7920 is a highly thermally conductive epoxy encapsulant developed to optimise thermal management in electric motors and power electronics.**

Through the use of innovative fillers, we achieve excellent thermal conductivity and at the same time the lowest possible level of abrasiveness, good workability and outstanding flow properties with our thermally conductive encapsulants. This profile of characteristics makes our systems perfect for use in the field of power electronics, battery technology and electric motors.

The amine-curing, two-component, black epoxy encapsulant 7500 + 7920 features a thermal conductivity of 1.2 W/mK and is especially designed for heat dissipation in modern electric motors and power electronics. Passes the UL94 V-0 test for layer thicknesses  $\geq 2$  mm.

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- + Thermal conductivity 1,2W/mK
- + Cold curing
- + Low viscosity at processing temperature
- + Self-levelling
- + Solvent-free and good chemical resistance



## Specifications

|  |                                     |
|--|-------------------------------------|
| <b>Product category</b>                                | Encapsulants   Thermal conductivity |
| <b>Chemical base</b>                                   | Epoxy                               |
| <b>Color</b>   | Black                               |
| <b>Density [g/cm<sup>3</sup>]</b>                      | 1.75 – 1.85                         |
| <b>Mixing ratio [by weight]</b>                        | 100 : 8.5                           |
| <b>Viscosity [mPas]</b>                                | 3 000 – 4 000                       |
| <b>Pot life [min]</b>                                  | 100                                 |
| <b>Shore hardness (DIN EN ISO 868)(DIN EN ISO 868)</b> | D80                                 |
| <b>Temperature range [°C]</b>                          | -40 – +165                          |
| <b>Curing conditions</b>                               | Cold curing                         |
| <b>Thermal conductivity [W/mK]</b>                     | 1.2                                 |
| <b>Glass transition temperature [°C]</b>               | 70                                  |
| <b>CTE &lt; Tg [ppm/K]</b>                             | 45                                  |
| <b>CTE &gt; Tg [ppm/K]</b>                             | 100                                 |
| <b>UL94</b>  | V0                                  |